

Wiring, Printed – Component

COMPANY
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E555217

Type	Cond Width			SS/ DSO	Max	Report	Surface Mount Technology	Assembly Solder Process Temp °C	Solder Limits °C	Solder sec	Max		Meets UL796 Class	C T	
	Min	Cond	Area		date	Oper					Flame				
	Min	Edge	Thk		DS/ Diam	After					Temp	Temp			
	mm	mm	mic		mm	2022- 01-01					°C	Cycles			°C
Multilayer metal base printed wiring boards, flammability only Recognition															
DI (ASP 1)	-	-	-	SS	-	Yes	Yes	260	2	288	10	-	V-0	-	-
Multilayer printed wiring boards															
HM (ASP 1)	0.10	0.13	17 Int:34	DS	50.8	Yes	Yes	260	2	288	20	130	V-0	All	*
HMI (ASP 1)	0.10	0.13	17 Int:34	DS	50.8	Yes	Yes	260	2	288	20	130	V-0	All	*
M (ASP 1)	0.075	0.10	12 Int:68	DS	50.8	Yes	Yes	260	2	288	20	130	V-0	All	*
Single layer metal base printed wiring boards															
AL1 (ASP 1)	0.13	0.15	17	SS	50.8	Yes	Yes	260	1	288	20	130	V-0	All	0
Single layer metal base printed wiring boards, flammability only Recognition															
AL2 (ASP 1)	-	-	-	DS	-	Yes	Yes	260	2	288	10	-	V-0	-	-
Single layer printed wiring boards															
D (ASP 1)	0.075	0.10	12	DS	50.8	Yes	Yes	260	2	288	20	130	V-0	All	*
HD (ASP 1)	0.10	0.13	17	DS	50.8	Yes	Yes	260	2	288	20	130	V-0	All	*

* – CTI marking is optional and may be marked on the printed wiring board.

(ASP 1) – Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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